

FEATURES

- Power pack
- Metal silicon junction ,majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss ,high efficiency
- High current capability ,low forward voltage drop
- High forward surge capability
- High frequency operation
- Meets MSL Level 1, per J-STD-020, LF MAX peak of 245°C (for TO-263 package)
- Solder bath temperature 275°C maximum, 10s, per JESD22-B106 (for TO-220AB and ITO-220AB package)
- Component in accordance to RoHS 2011/65/EU



MECHANICAL DATA

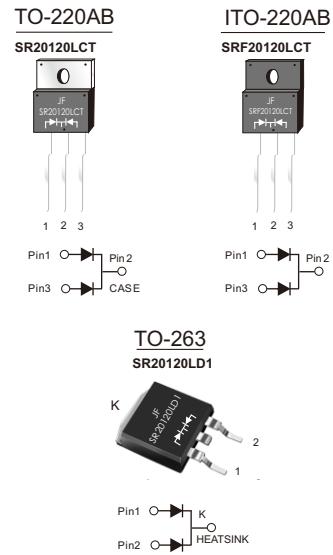
- Case: JEDEC TO-220AB、ITO-220AB、TO-263
- Molding compound meets UL94V-0 flammability rating
- Terminals: Lead solderable per J-STD-002 and JESD22-B102
- Polarity: As marked
- Mounting Torque: 10 in-lbs maximum

TYPICAL APPLICATIONS

For use in low voltage ,high frequency inverters ,DC/DC converters, free wheeling ,and polarity protection applications

MAXIMUM RATINGS

(Ratings at 25°C ambient temperature unless otherwise specified)



PRIMARY CHARACTERISTICS	
I _F (AV)	2×10A
V _{RRM}	120V
I _{FSM}	200A
V _F at I _F =10.0A,Per leg,25°C	0.82V
I _R	12 μA
T _J (MAX)	150°C
Package	TO-220AB, ITO-220AB, TO-263
Diode variations	Common cathode

Parameter	Symbol	SR20120LCT, SRF20120LCT, SR20120LD1	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	120	V
Maximum average forward rectified current (see fig.1)	Per leg	I _F (AV)	A
	Total device		
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	I _{FSM}	200	A
Peak repetitive reverse current per diode at t _p =2 μs 1KHz	I _{RRM}	0.5	A
Operating junction and Storage temperature range	T _J , T _{Stg}	-55 to +150	°C
Isolation voltage (ITO-220AB only) from terminals to heatsink t=1 min	V _{AC}	1500	V

RATINGS AND CHARACTERISTIC OF SR20120LCT,SRF20120LCT,SR20120LD1

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ C$ Unless otherwise noted)

Parameter	Test Conditions		Symbol	TYP.	MAX.	Unit
Instantaneous forward voltage	Per leg $I_F=10.0A$	$T_A=25^\circ C$	V_F ¹⁾	0.82	0.85	V
		$T_A=100^\circ C$		0.69	—	
		$T_A=125^\circ C$		0.65	—	
		$T_A=25^\circ C$		0.65	—	
	Per leg $I_F=5.0A$	$T_A=100^\circ C$		0.58	—	mA
		$T_A=125^\circ C$		0.55	—	
		$T_A=25^\circ C$		12	50	μA
		$T_A=100^\circ C$		2.5	—	
		$T_A=125^\circ C$		10	—	
Typical junction capacitance	4V,1MHz		C_J	400		pF

Notes: 1.Pulse test: 300 μs pulse width,1% duty cycle

2.Pulse test: pulse width $\leqslant 40ms$

THERMAL CHARACTERISTICS ($T_A=25^\circ C$ Unless otherwise noted)

Parameter	Symbol	SR20120LCT	SRF20120LCT	SR20120LD1	Unit
Typical thermal resistance ³⁾	$R_{\theta JC}$	2.5	4.5	2.5	$^\circ C/W$

3.Thermal resistance from junction to case

AVAILABALE PACK INFORMATION

Product code	Pack	Box Size L×W×H(mm)	Quantity(pcs/box)	Carton SizeL×W×H(mm)	Quantity(box/carton)
SR20120LCT-TO-220AB	P/T	558×148×38	1000	565×225×170	5
SRF20120LCT-ITO-220AB	P/T	558×148×38	1000	565×225×170	5
SR20120LD1-TO-263	P/T	558×148×38	1000	565×225×170	5

RATINGS AND CHARACTERISTIC OF SR20120LCT,SRF20120LCT,SR20120LD1

FIG.1-FORWARD CURRENT DERATING CURVE

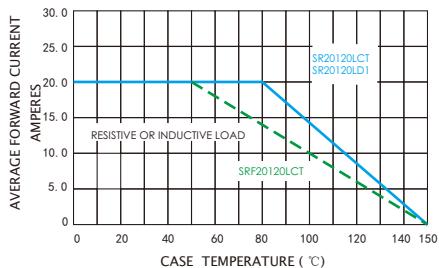


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

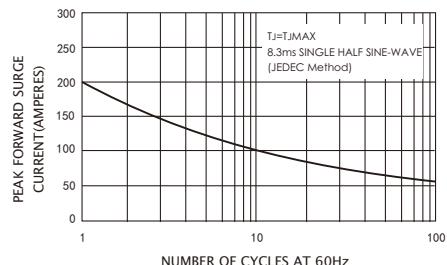


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

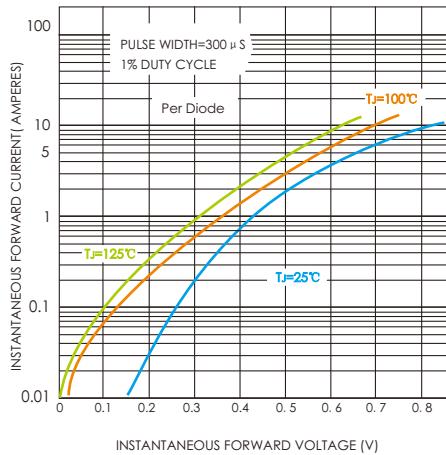


FIG.4-TYPICAL REVERSE CHARACTERISTICS

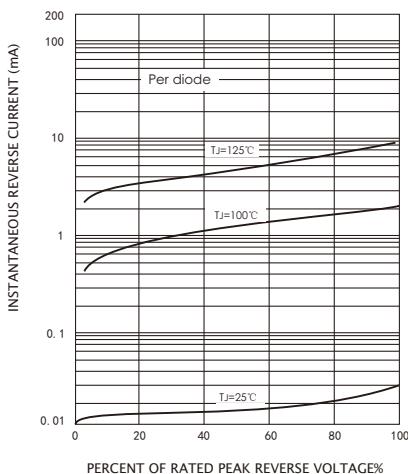
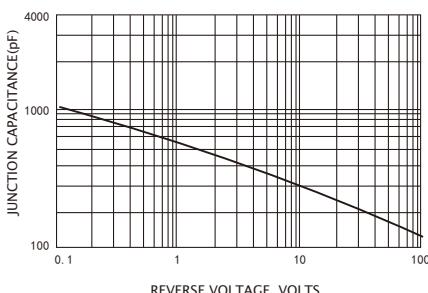


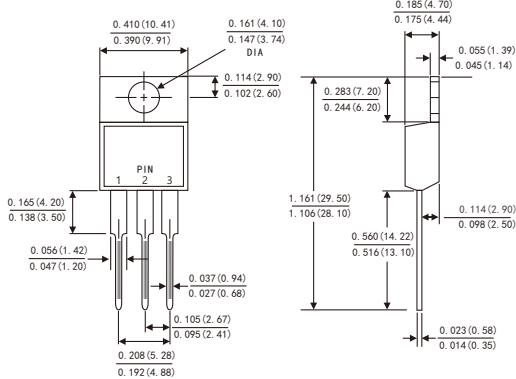
FIG.5-TYPICAL JUNCTION CAPACITANCE



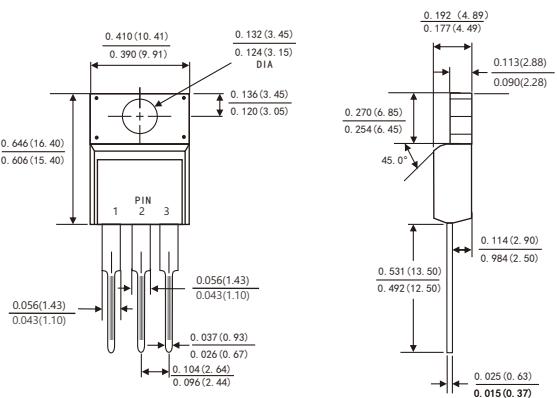
PACKAGE OUTLINE DIMENSIONS

Dimensions in inches and (millimeters)

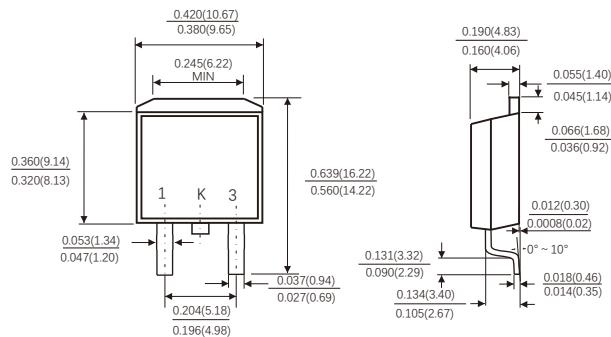
TO-220AB



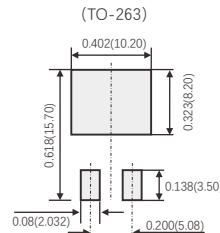
ITO-220AB



TO-263



Suggested Pad Layout



(设计者可参考推荐值根据焊接工艺
要求自行确定适合的焊盘尺寸)
(Designers can refer to the recommended
values according to the manufacturing process
requirements to determine the appropriate pad size)

Dimensions in inches and (millimeters)